

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
WENLONG XU	01/18/2019
<b>RECEIVING PARTY DATA</b>	
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<b>City:</b>	SHENZHEN
<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	29677993
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<b>Fax Number:</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	JXPT1903002
<b>NAME OF SUBMITTER:</b>	RAYMOND J. CHEW
<b>SIGNATURE:</b>	/Raymond J. Chew/
<b>DATE SIGNED:</b>	01/25/2019
<b>Total Attachments: 2</b>	
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source=JXPT1903002-Assignment#page2.tif	

**ASSIGNMENT**

WENLONG XU having a mailing address 1501, UNIT B, 4th BUILDING, 3rd PERIOD,  
WAN KE JIN SE LING YU GARDEN, FU YONG, BAOAN DISTRICT, SHENZHEN, G  
UANGDONG, CHINA. (hereafter referred to as the undersigned), is the inventor of the U.S. pat  
ent application to be filed entitled:

**FAN**

The above U.S. application was assigned serial no. \_\_\_\_\_ and was filed on \_\_\_\_\_. The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

ShenZhen TopSharp Precision Electronics Co., Ltd. Having a place of business 3th,  
8th Floor, Building 1st, HuaFeng 1st Technology Park, B District, SanWei, XiXiang, BaoAn,  
ShenZhen, China (hereafter referred to as the assignee), is desirous of acquiring the entire right, title and interest in the above-identified application, in said invention described therein, all applications for and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, in any subsequent non-provisional applications filed for this invention or improvements thereto, and all divisions and continuations thereof, any Registered Community Design applications, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

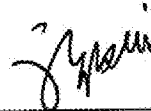
It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention

Attorney Docket No.: JXPT1903002  
Customer No.: 128477

throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrant that the rights and property herein conveyed are free and clear of any encumbrance. EXECUTED under seal on the following date January 18, 2019.

Date



\_\_\_\_\_  
WENLONG XU